

### Description

**Dymax UV adhesives** cure in seconds when exposed to <u>high intensity UV light</u>, and find many applications as adhesives for electronics assembly. The "on demand" cure feature of these resins means no rework as a result of adhesive migrating onto solder pads or through holes. Dymax adhesives for electronic assembly are ideal for bonding heat sinks and heat sensitive components, wire and component tacking, strain relief of large parts and securing hand inserted components prior to wave soldering. Single part UV light curing adhesives can give productivity gains over two part systems like epoxies, and slower curing chemistries like silicones.

These one-part, solvent-free adhesives are electrically insulating, and are particularly useful for:

- Wire tacking and component ruggedisation
- BGA and leadless component support
- Strain relief, supporting larger electronic components
- Thermal management, heat sink bonding
- Shallow potting

### Features & Benefits





- Single part formulations
- Cure on-demand only upon exposure to UV light
- Excellent adhesion
- Precise and easy dispensing
- Room temperature storage unlimited pot life

#### **Selector Guide**

Product data sheets available on request.



#### **Electronics adhesives**

These adhesives provide optimal circuit protection. Their "on-demand" cure feature makes them ideal for manual applications such as wire tacking and coil termination, where optimal placement and immediate strength is critical.

Product	Applications	Features
<b>Dymax 9-911-REV-B</b> DYM 9-911-REV-B	Wire tacking/coil termination	On-demand cure for optimal positioning; easily dispensed by hand; exposed areas cure in seconds for immediate strength; shadowed areas may cure with heat over time
<b>Dymax 910</b> DYM 910	Wire and parts tacking; strain relief; unitising	Flexible; good adhesion; mechanically removable
<b>Dymax 914-A</b> DYM 914-A	Wire tacking on PCB's; for manual and fully automated dispensing systems	Good insulation qualities; shock absorbing; deep cure capability; bonds well to porous surfaces; rapid cure speed



#### **Component ruggedising**

Dymax component ruggedizing and staking materials are engineered to hold critical components, such as Ball Grid Arrays (BGA) and Video Graphics Arrays (VGA), for secondary processes or for long-term reliability. Each material helps enhance shock and vibration resistance of electronic assemblies.

Product	Applications	Features
<b>Dymax 9422-SC</b> DYM 9422-SC	Reinforcing fine pitch or leadless components; underfill replacement; staking	Fast, room-temperature cure; adhesion to various PCB substrates; low modulus for reducing stress on board components; highly thixotropic for minimal movement after dispense; See-Cure adhesives appear blue when dispensed and become clear for easy verification of cure; halogen- free



Product	Applications	Features
<b>Dymax 9309-SC</b> DYM 9309-SC	Reinforcing fine pitch or leadless components; underfill alternative; shock absorption	Tack-free cure; compatible with both needle and jet dispensing equipment; adhesion to various PCB substrates; reduces stress on board components; highly thixotropic for minimal movement after dispense; See- Cure adhesives appear blue when dispensed and become clear for easy verification of cure; halogen-free

#### Potting & sealing

Dymax light cure UV potting materials cure tack-free in seconds upon exposure to UV/Visible light. Each potting compound is engineered to bond different substrates, offering tenacious adhesion to plastics and metals. UV potting resins reduce waste from off-ratio mixing and are free from isocyanates and heavy metals. Processing in seconds eliminates fixtures, jigs, racks, and ovens to increase space and lower total inventory costs.



Product	Applications	Features
<b>Dymax 921 series</b> DYM 921	Potting; ruggedising heavy components	Urethane acrylate; light cure in seconds; secondary heat cure; one part, no mixing is required; multiple viscosities; visible light cure for maximum cure depth; adhesion to filled plastics including PBT/Valox®

#### Thermal management

Dymax Multi-Cure<sup>®</sup> thermal interface materials may be cured with light, heat, or activator. Most applications utilise a combination of these methods for optimal cure speed. Light cure allows for exposed areas to cure immediately, fixturing parts in place so the activator or heat can continue curing in shadowed areas without interruption to process flow.

Product

**Applications** 

Features



<b>Dymax 9-20801</b> DYM 9-20801	Adhesive paste	Thermally conductive; 1.2 W/mK; UV/Visible light cure for exposed areas in seconds; activator or heat cure shadowed areas; one part; solvent free
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#### Safety Data Sheets

For the latest SDS for this product, please e-mail msds@intertronics.co.uk

### Watch UV Curing

Click the image below to watch UV Curing Adhesives in action:



### **Other Information**

Our Technical Resources page has links to:

- Technical Bulletin: <u>Wire Tacking The Options</u>
- Article: Case Histories of Light Curing Adhesives in Electronics Manufacturing

Article: <u>Advances in Light Curing Adhesives and Coatings Lead to Process and Quality Benefits in</u> <u>Electronics Manufacturing</u>

### **Ordering Information**





- Name\*
- Company\*
- Phone\*
- Email\*
- Post code\*

If you're in the UK, knowing your postcode would help us get in touch even more quickly. If you're outside the UK, please indicate your country.

Tell us about your application



Any information that you submit using this form will be processed according to our privacy policy.

Phone This field is for validation purposes and should be left unchanged. Submit

Supplied by:

# *intertronics*

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Last updated: November 2022 Version: 4.7

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